



CTN2304 N-Channel Enhancement Mode MOSFET

Features

- 30V/2.5A,R_{DS(ON)}=117 mΩ @V_{GS}=10V
- 20V/2.4A,R_{DS(ON)}=190 mΩ @V_{GS}=4.5V
- Super high density cell design for extremely low R_{DS(ON)}
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3L package design

Applications

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

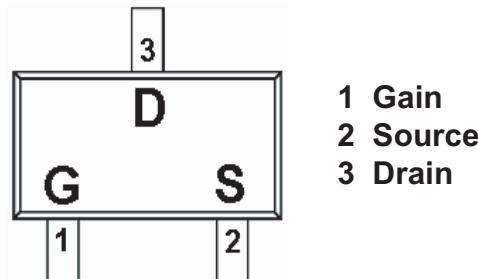
Description

The CTN2304 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

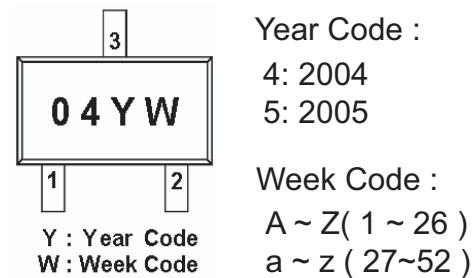
Pin Configuration (SOT-23-3L)



Ordering Information

Part Number	Package	Part Marking
CTN2304S23RP	SOT-23-3L	04YW

Note: Suffix "P" means Pb - Free products.



**Absolute Maximum Ratings** ($T_A=25^\circ\text{C}$ Unless otherwise noted)

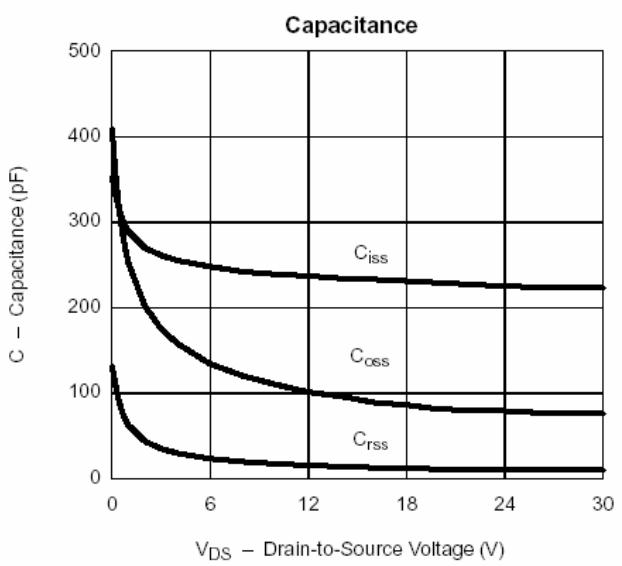
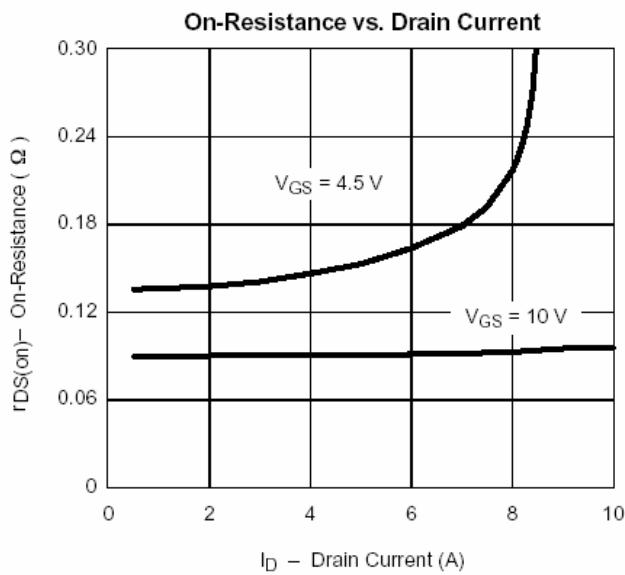
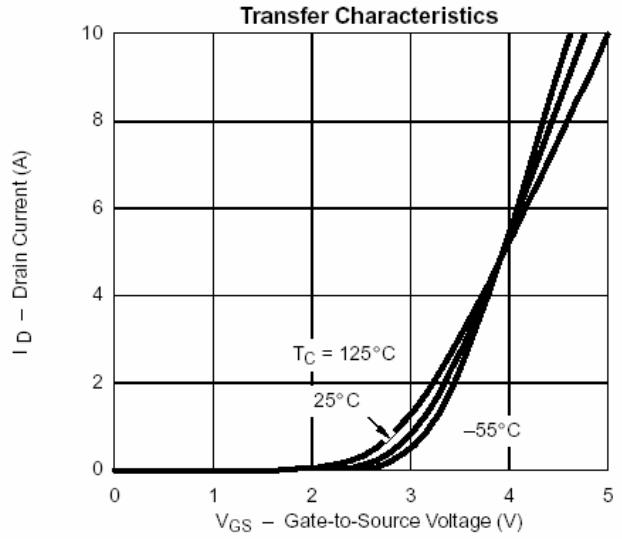
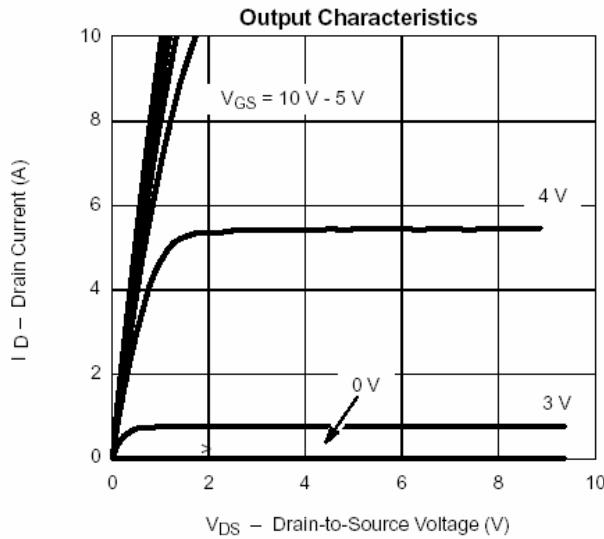
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current($T_J=150^\circ\text{C}$)	I_D	2.5	A
		2.0	
Pulsed Drain Current	I_{DM}	10	A
Continuous Source Current(Diode Conduction)	I_S	1.25	A
Power Dissipation	P_D	1.25	W
		0.8	
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	R_{thJA}	100	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0		3.0	
Gate Leakage Current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$			1	uA
		$V_{DS}=30\text{V}, V_{GS}=0\text{V}$			10	
		$T_J=55^\circ\text{C}$				
On-State Drain Current	$I_{D(\text{on})}$	$V_{DS}\geq 4.5\text{V}, V_{GS}=10\text{V}$	6			A
		$V_{DS}\geq 4.5\text{V}, V_{GS}=4.5\text{V}$	4			
Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS}=10\text{V}, I_D=2.5\text{A}$		0.092	0.117	Ohm
		$V_{GS}=4.5\text{V}, I_D=2.0\text{A}$		0.142	0.190	
Forward Transconductance	g_{fs}	$V_{DS}=4.5\text{V}, I_D=2.5\text{A}$		4.6		S
Diode Forward Voltage	V_{SD}	$I_S=1.25\text{A}, V_{GS}=0\text{V}$		0.77	1.2	V
Total Gate Charge	Q_g	$V_{DS}=15\text{V}, V_{GS}=10\text{V}$ $I_D \geq 2.5\text{A}$		4.5	10	nC
Gate-Source Charge	Q_{gs}			0.8		
Gate-Drain Charge	Q_{gd}			1.0		
Input Capacitance	C_{iss}	$V_{DS}=15\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		240		pF
Output Capacitance	C_{oss}			110		
Reverse Transfer Capacitance	C_{rss}			17		
Turn-On Time	$t_{d(on)}$	$V_{DD}=15\text{V}, R_L=15\text{Ohm}$ $I_D \geq 1.0\text{A}, V_{GEN}=10\text{V}$ $R_G=6\text{Ohm}$		8	20	ns
	t_r			12	30	
Turn-Off Time	$t_{d(off)}$			17	35	
	t_f			82	0	

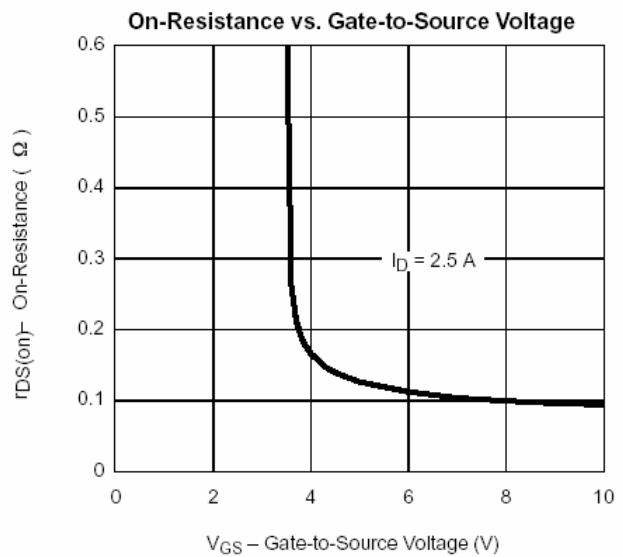
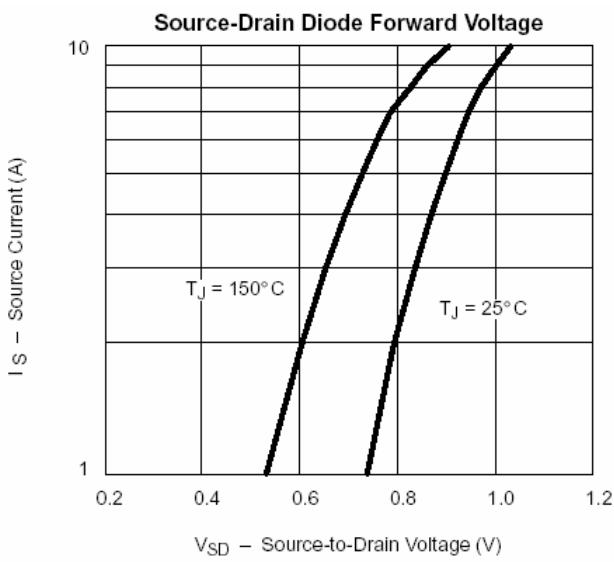
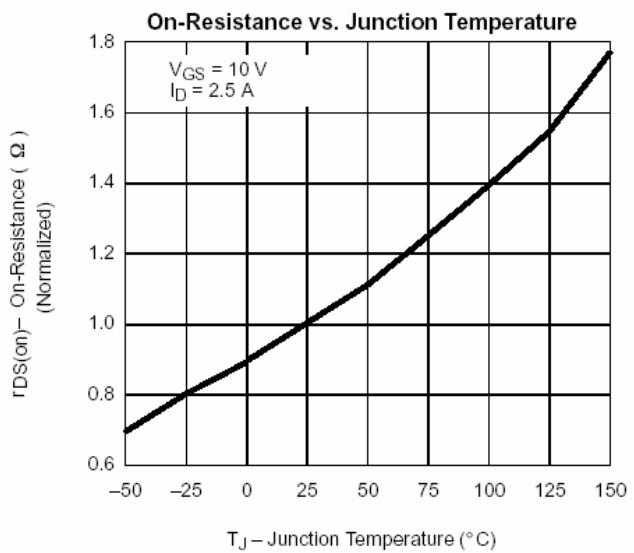
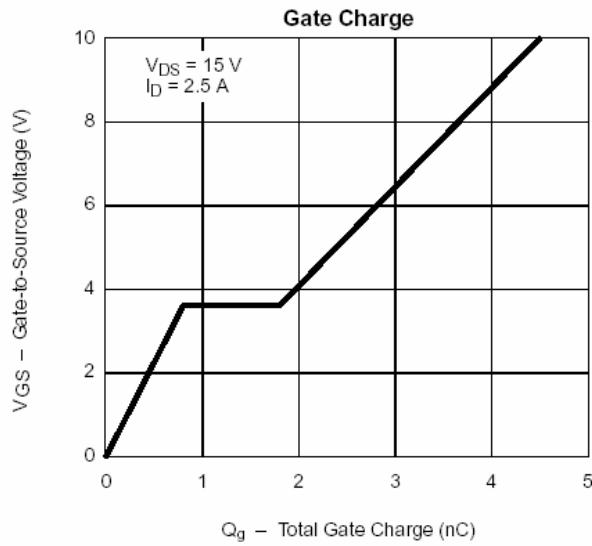


Typical Characteristics Curves



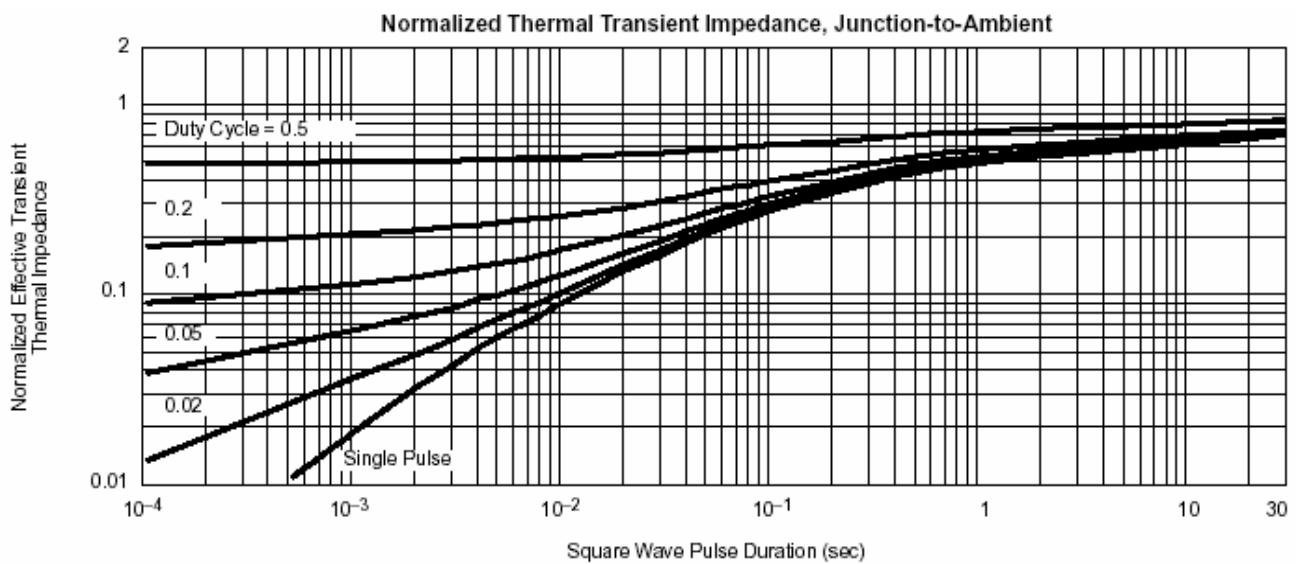
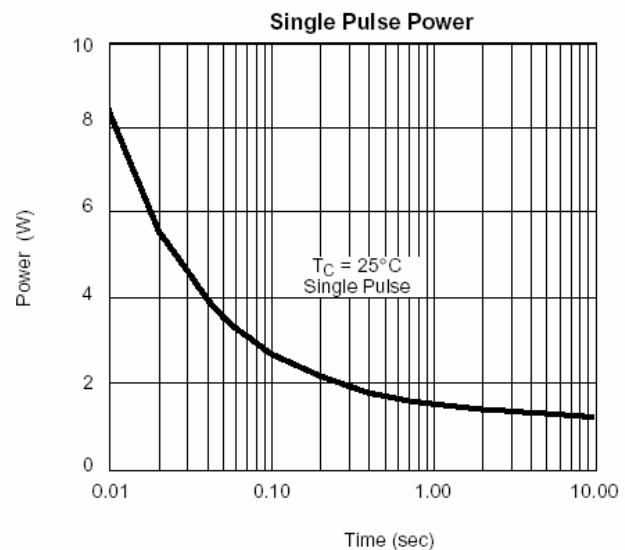
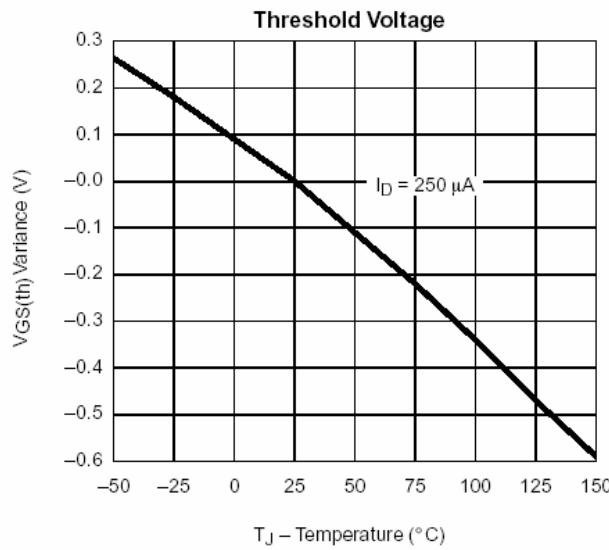


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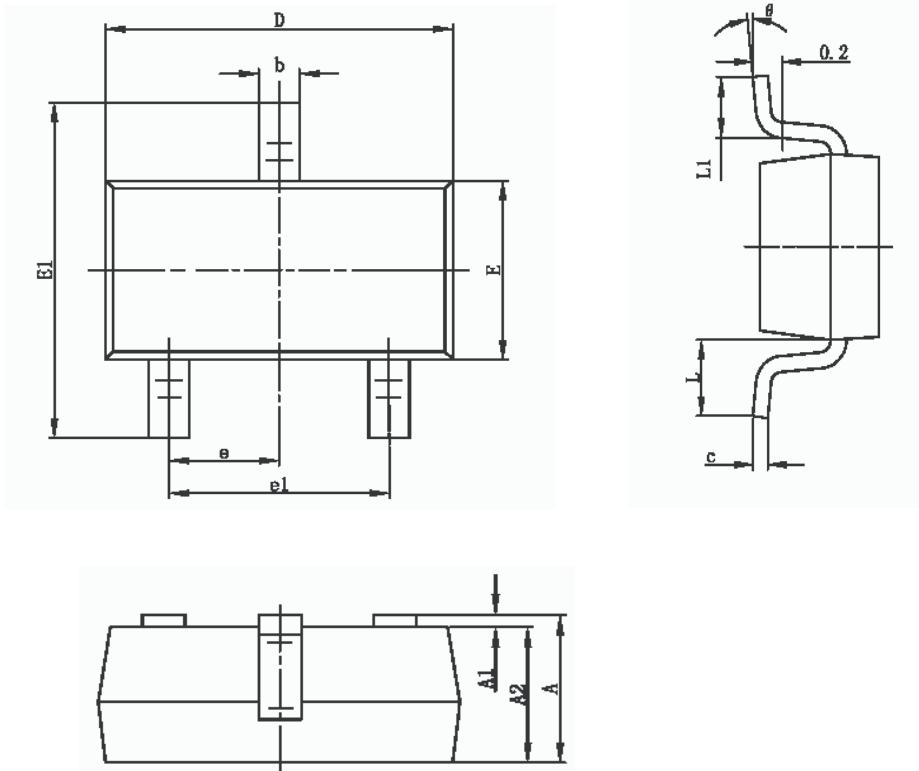


Typical Characteristics Curves





Package Outline



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
B	0.300	0.400	0.012	0.016
C	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950	TYP	0.037	TYP
e1	1.800	2.000	0.071	0.079
L	0.700	REF	0.028	REF
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°